

**PATENT**



**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

**Application of:**

**Salman Akram**

**Serial No.: 09/388,031**

**Filed: September 1, 1999**

**For: METALLIZATION STRUCTURES  
FOR SEMICONDUCTOR DEVICE  
INTERCONNECTS, METHODS FOR  
MAKING SAME, AND  
SEMICONDUCTOR DEVICES  
INCLUDING SAME**

**Examiner: E. Lee**

**Group Art Unit: 2815**

**Attorney Docket No.: 3442US (96-428)**

**CERTIFICATE OF MAILING**

I hereby certify that this correspondence along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail (under 37 C.F.R. § 1.8(a)) on the date of deposit shown below with sufficient postage and in an envelope addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231.

June 26, 2001  
Date of Deposit

Signature of registered practitioner or other person having reasonable basis to expect mailing to occur on date of deposit shown pursuant to 37 C.F.R. § 1.8(a)(1)(ii)

Darlene Holt  
Typed/printed name of person whose signature is contained above

**AMENDMENT**

Box Non Fee Amendment  
Commissioner for Patents  
Washington, D.C. 20231

Sir:

The following amendments and remarks are filed in response to the Examiner's remarks in the Office Action mailed March 29, 2001, the three-month shortened statutory period for response to which expires on June 29, 2001.